PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3947055

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WEI MA	11/03/2014
WAI HUNG	11/03/2014
FRANCIS GUILLEN GAMBOA	11/03/2014
XIAOMING YU	11/03/2014
DENNIS TAK KIT TONG	11/03/2014

RECEIVING PARTY DATA

Name:	SAE MAGNETICS (H.K.) LTD.
Street Address:	SAE TECHNOLOGY CENTRE, 6 SCIENCE PARK EAST AVENUE, HONG KONG SCIENCE PARK, SHATIN, N.T.
City:	HONG KONG
State/Country:	HONG KONG

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15201519

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: charles_ho@barron-young.com
Correspondent Name: B.Y.I.P., LTD
Address Line 1: P.O. BOX 1484 OF GENERAL POST OFFICE
Address Line 4: HONG KONG, HONG KONG

ATTORNEY DOCKET NUMBER:	SAE-1604-USCON
NAME OF SUBMITTER:	CHARLES S. HO
SIGNATURE:	/charles ho/
DATE SIGNED:	07/05/2016

Total Attachments: 5

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ASSIGNMENT - Patent Application	Docket Number: SAE-1604-USCON

Whereas, the Assignor, comprising the following named inventors:

ASSIGNOR(s)/ INVENTOR(s)	**Wei Ma**

made an invention entitled: **WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME**

for which an application for Letters Patent of the United States:
(Select one of the following):

☒ is executed concurrently herewith
☐ was filed in the U.S. Patent and Trademark Office on ___________,
as U.S. Patent Application Serial No.: __________

ASSIGNEE (Full Name, Address and Country)	**SAE Magnetics (H.K.) Ltd.** **SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.** **Hong Kong**

is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor,

Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar ($1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto.

Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.

In witness whereof, this Assignment is executed on the day indicated below.

	Typed or Printed Name	Signature	Date
SIGNATURE	**Wei Ma**	X	X 3-11-2014
	KA LAP TONG * Witness to Assignor	X Lap * Witness to Assignor	X 3-Nov-14

ASSIGNMENT - Patent Application	Docket Number: SAE-1604-USCON

Whereas, the Assignor, comprising the following named inventors:

ASSIGNOR(s)/ INVENTOR(s)	**Wai Hung**

made an invention entitled: **WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME**

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In witness whereof, this Assignment is executed on the day indicated below.

	Typed or Printed Name	Signature	Date
SIGNATURE	**Wai Hung**	X	X 3-NOV-2014
	KA LAP TONG * Witness to Assignor	X Lap * Witness to Assignor	X 3-Nov-14

ASSIGNMENT - Patent Application	Docket Number: SAE-1604-USCON

Whereas, the Assignor, comprising the following named inventors:

ASSIGNOR(s)/ INVENTOR(s)	**Francis Guillen Gamboa**

made an invention entitled: **WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME**

for which an application for Letters Patent of the United States:
(Select one of the following):

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☐ was filed in the U.S. Patent and Trademark Office on ___________,
as U.S. Patent Application Serial No.: __________

ASSIGNEE (Full Name, Address and Country)	**SAE Magnetics (H.K.) Ltd.** **SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.** **Hong Kong**

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In witness whereof, this Assignment is executed on the day indicated below.

	Typed or Printed Name	Signature	Date
SIGNATURE	**Francis Guillen Gamboa**	X	X 03 NOV-2014
	KA LAP, TONG * Witness to Assignor	X * Witness to Assignor	X 3-Nov-14

ASSIGNMENT - Patent Application

Docket Number: SAE-1604-USCON

Whereas, the Assignor, comprising the following named inventors:

ASSIGNOR(s)/ INVENTOR(s)	**Xiaoming Yu**

made an invention entitled: **WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME**

for which an application for Letters Patent of the United States:
(Select one of the following):

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ASSIGNEE (Full Name, Address and Country)	**SAE Magnetics (H.K.) Ltd.** **SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.** **Hong Kong**

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In witness whereof, this Assignment is executed on the day indicated below.

	Typed or Printed Name	Signature	Date
SIGNATURE	**Xiaoming Yu**	X yu Xiaoming	X 3/Nov/2014
	KA LAP, TONG. * Witness to Assignor	X Lap. * Witness to Assignor	X 3-Nov-14

ASSIGNMENT - Patent Application	Docket Number: SAE-1604-USCON

Whereas, the Assignor, comprising the following named inventors:

ASSIGNOR(s)/ INVENTOR(s)	**Dennis Tak Kit Tong**

made an invention entitled: **WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME**

for which an application for Letters Patent of the United States:
(Select one of the following):

☒ is executed concurrently herewith
☐ was filed in the U.S. Patent and Trademark Office on ___________,
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ASSIGNEE (Full Name, Address and Country)	**SAE Magnetics (H.K.) Ltd.** **SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.** **Hong Kong**

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In witness whereof, this Assignment is executed on the day indicated below.

	Typed or Printed Name	Signature	Date
SIGNATURE	**Dennis Tak Kit Tong**	X	X 3-Nov-2014
	KA LAP TONG * Witness to Assignor	X * Witness to Assignor	X 3-Nov-14